

# **Thermal Monitor**

#### FEATURES

- On-Chip Temperature Transducer
- Temperature Comparator Gives
  Threshold Temperature Alarm
- Power Reference Permits Airflow
  Diagnostics
- Precision 2.5V Power Reference Permits Airflow Diagnostics
- Transducer Output is Easily Scaled for Increased Sensitivity
- Low 2.5mA Quiescent Current

#### DESCRIPTION

The UC1730 family of integrated circuit devices are designed to be used in a number of thermal monitoring applications. Each IC combines a temperature transducer, precision reference, and temperature comparator allowing the device to respond with a logic output if temperatures exceed a user programmed level. The reference on these devices is capable of supplying in excess of 250mA of output current – by setting a level of power dissipation the rise in die temperature will vary with airflow past the package, allowing the IC to respond to airflow conditions

UC1730

UC2730

UC3730

These devices come in an 8-Pin DIP, plastic or ceramic, a 5-Pin TO-220 or a PLCC-20 version. In the 8-Pin version, a PTAT (proportional to absolute temperature) output reports die temperature directly. This output is configured such that its output level can be easily scaled up with two external gain resistors. A second PTAT source is internally referenced to the temperature comparator. The other input to this comparator can then be externally programmed to set a temperature threshold. When this temperature threshold is exceeded an alarm delay output is activated. Following the activation of the delay output, a separate open collector output is turned on. The delay pin can be programmed with an external RC to provide a time separation between activation of the delay pin and the alarm pin, permitting shutdown diagnostics in applications where the open collector outputs of multiple parts are wire OR'ed together.

The 5-Pin version in the TO-220 package is well suited for monitoring heatsink temperatures. Enhanced airflow sensitivities can be obtained with this package by mounting the device to a small heatsink in the airstream. This version of the device does not include the PTAT output or the open collector alarm output.



#### **BLOCK DIAGRAM**

### UC1730 UC2730 UC3730

### **ABSOLUTE MAXIMUM RATINGS**

Input Supply Voltage, (+VIN)
Alarm Output Voltage (8-Pin Version Only) 40V
Alarm Delay Voltage 10V
Alarm Threshold Set Voltage 10V
2.5V Reference Output Current
Alarm Output Current (8-Pin Version Only) 0 mA
Power Dissipation at TA = 25°C (Note 2) 1000 mW
Power Dissipation at Tc = 25°C (Note 2) 2000 mW
Thermal Resistance Junction to Ambient
N, 8-Pin Plastic DIP 110°C/W
J, 8-Pin Ceramic DIP 110°C/W

#### CONNECTION DIAGRAMS



T, 5-Pin Plastic DIP TO-220 65°C/W
Thermal Resistance Junction to Case
N, 8-Pin Plastic DIP 60°C/W
J, 8-Pin Ceramic DIP 40°C/W
T, 5-Pin Plastic TO-220 5°C/W
Operating Junction Temperature
Storage Temperature
Lead Temperature (Soldering, 10 Seconds)
Note 1: Voltages are referenced to ground. Currents are posi-
tive into, negative out of, the specified terminals.

Note 2: Consult Packaging section of Databook for thermal limitations and considerations of package.

& Fackage	PACKAGE PIN FUNCTION		
	FUNCTION	PIN	
	N/C	1-3	
3 2 1 20 19	ALARM DELAY	4	
	ALARM OUTPUT	5	
	+VIN	6	
5 17	GND	7	
<b>[</b> 6 16]	N/C	8-13	
<b>₫ 7 15</b> ₽	PTAT+	14	
8 10 11 10 10	PTAT-	15	
9 10 11 12 13	2.5V REFERENCE	16	
	2.5V REFERENCE	17	
	ALARM THRESHOLD SET	18	
	N/C	19-20	

**ELECTRICAL CHARACTERISTICS:** Unless otherwise stated, these specifications apply for  $T_J = 0^{\circ}C$  to +100°C for the UC3730, -25°C to +100°C for the UC2730 and -55°C to +125°C for the UC1730, +VIN = + 5V, and PTAT- = 0V. TA = TJ.

PARAMETERS	TEST CONDITIONS	MIN	TYP	MAX	UNITS			
INPUT SUPPLY								
Supply Current	+VIN = 35V		2.8	4.0	mA			
	+VIN = 5V		2.3	3.5	mA			
REFERENCE								
Output Voltage	TJ = 25°C	2.475	2.5	2.525	V			
	Over Temperature	2.46		2.54	V			
Load Regulation	IOUT = 0 to 250mA		8.0	25	mV			
Line Regulation	+VIN = 5 to 25V		1.0	5.0	mV			
TEMPERATURE COMPARATOR								
Temperature Comparator Threshold	at 300°K (26.85°C), Nominally 5mV/°K, VINPUT High to Low	1.475	1.50	1.525	V			
Temperature Error		-10		10	°C			
Threshold Line Regulation	+VIN = 5 to 25V		0.005	0.02	%/V			
Temperature Linearity	Note 2		2.0	5.0	°C			
Threshold Hysteresis		3.0	8.0	15	mV			
Input Bias Current	VINPUT at 1.5V	-0.5	-0.1		μA			
Max Output Current	Vout = 1V	1.2	3.0		mA			
Output Sat Voltage	Ιουτ = 100μΑ	ſ	0.05	0.25	V			

#### UC1730 UC2730 UC3730

# **ELECTRICAL**

Unless otherwise stated, these specifications apply for  $T_J = 0^{\circ}C$  to +100°C for the UC3730, **CHARACTERISTICS (cont):** -25°C to + 100°C for the UC2730 and -55°C to +125°C for the UC1730, +VIN = + 5V, and PTAT = 0V. TA = TJ.

PARAMETERS	TEST CONDITIONS	MIN	TYP	MAX	UNIT			
TEMPERATURE COMPARATOR (cont.)								
Output Leakage Current	Vout = 1V		0.01	1.0	μA			
PTAT BUFFER (8-Pin N, or J Version Only)								
Output Voltage	at 300°K (26.85°C), Nominally 5mV/°K	1.460	1.50	1.54	V			
	In 10X Config. + VIN = 25V	14.6	15	15.4	V			
Temperature Error		-12		12	°C			
Temperature Linearity (Note 2)			2.0	5.0	°C			
Line Regulation	+VIN = 5 to 25V		0.02	0.04	%/V			
Load Regulation	IOUT = 0 to 2mA		1.0	3.0	mV			
Dropout Voltage	PTAT + TO +VIN		1.9	2.5	V			
Input Bias Current at PTAT- Input		-3.0	-1.0		μA			
ALARM BUFFER COMPARATOR (8-	Pin N, or J Version Only)	-			-			
Threshold Voltage (Vтн)	Alarm Delay Input Low to High	1.1	1.2	1.3	V			
Threshold Hysteresis Voltage	Alarm Delay Voltage > Vтн		100	250	mV			
Input Bias Current	Alarm Delay Voltage < Vтн		0.1	0.5	μA			
Max Output Current	Vout = 1V	7.0	15		mA			
Output Sat Voltage	IOUT = 3mA		0.25	0.45	V			
Output Leakage	Vout = 35V		0.1	2.0	μA			

Note 2: This parameter is guaranteed by design and is not tested in production.

## APPLICATIONS AND OPERATION INFORMATION



**VREF Maximum Output Current vs Input Supply** 

Junction Temperature Rise vs Airflow UC3730N (8-Pin Plastic Dip)

#### **APPLICATIONS AND OPERATION INFORMATION (Cont.)**





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#### PACKAGING INFORMATION

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
UC2730N	OBSOLETE	PDIP	Р	8	TBD	Call TI	Call TI
UC2730T	OBSOLETE	TO-220	KC	5	TBD	Call TI	Call TI
UC3730N	OBSOLETE	PDIP	Р	8	TBD	Call TI	Call TI
UC3730Q	OBSOLETE	PLCC	FN	20	TBD	Call TI	Call TI
UC3730QTR	OBSOLETE	PLCC	FN	20	TBD	Call TI	Call TI
UC3730T	OBSOLETE	TO-220	KC	5	TBD	Call TI	Call TI

<sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details. **TBD:** The Pb-Free/Green conversion plan has not been defined.

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<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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